



Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

Compaq Presario CQ50

Compaq Presario CQ60

Compaq Presario CQ70

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother Board	1
Batteries	All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries batteries	1
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps LCD unit	1
Cathode Ray Tubes (CRT)	No	0
Capacitors / condensers (Containing PCB/PCT)	No	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	No	0
External electrical cables and cords	No	0
Gas Discharge Lamps	No	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	No	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. No	0
Components and waste containing asbestos	No	0

Components, parts and materials containing refractory ceramic fibers	No	0
Components, parts and materials containing radioactive substances	No	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Power driver	
Description #2 hand driver	
Description #3 Fixture (Holding support MB)	
Description #4 Fixture (Holding support ODD/LCD/HDD)	
Description #5	

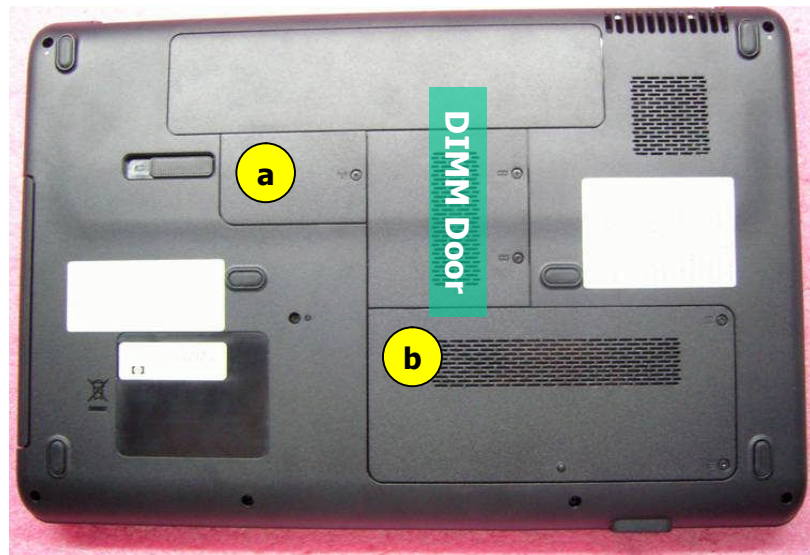
3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take down BTY direct from system bottom side (Get: BTY)
2. Take down Wireless door/screw/antenna; (Get: Wireless)
3. Take down HDD door/Screw (Get: HDD module)
4. Take down bottom side screw (Get: ODD)
5. Transfer to Top side/Open LCD,take down KB direct (Get: KB)
6. Cramp out power cable (Get: Middel cover)
7. Take down Top of base unit screw/Cable (Get :Base module/LCD module)
8. Take dow Bezel/LCD module screw; (Get: LCD/Inveter/Camera)
9. Take down U-case module (Get: U-case module)
10. Take screw/Cable in base module (Get: USB board/Audio board/BT board/Speaker/MB/DIMM)
11. Take down heat sink in MB (Get:CPU)
12. Take down T/P bracket in U-case module (Get: T/P/T/P on-off botton/T/P L-R botton)

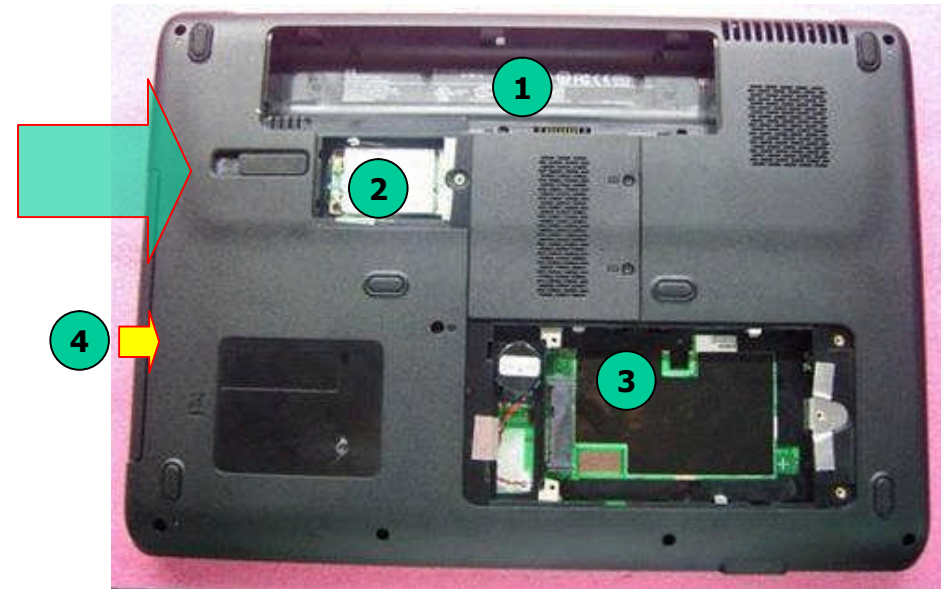
3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Disassemble Process-1



Get Component

- 1.BTY
- 2.Wireless
- 3.HDD module
- 4.ODD module



Disassemble Item

a. Wireless Door

b. HDD Door

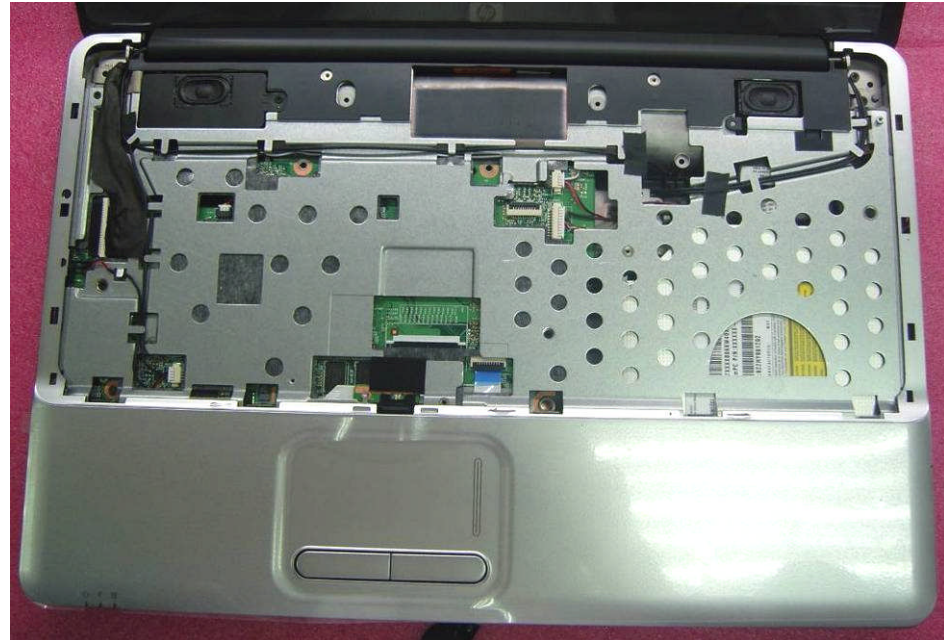
Screw

(Tear down all screw in bottom side except DIMM Door)

Disassemble Process-2

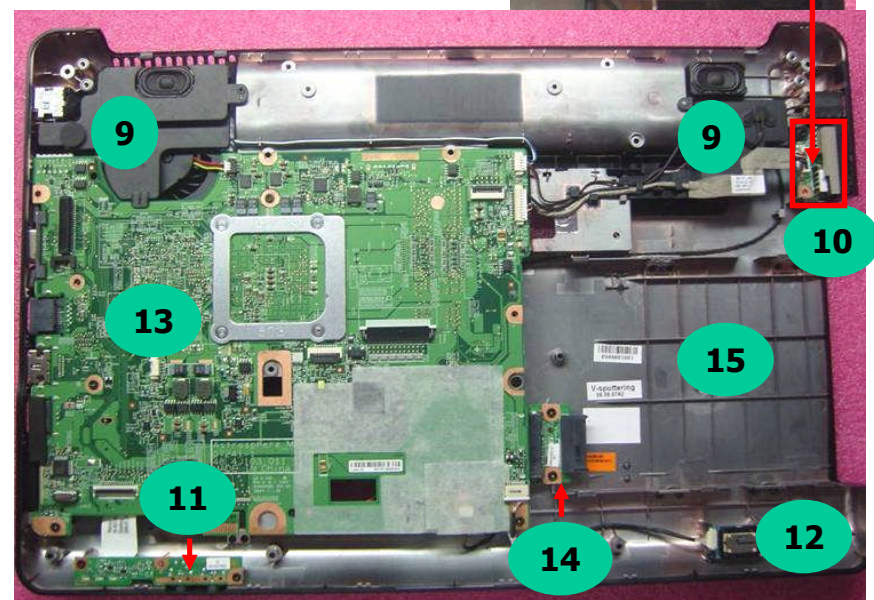
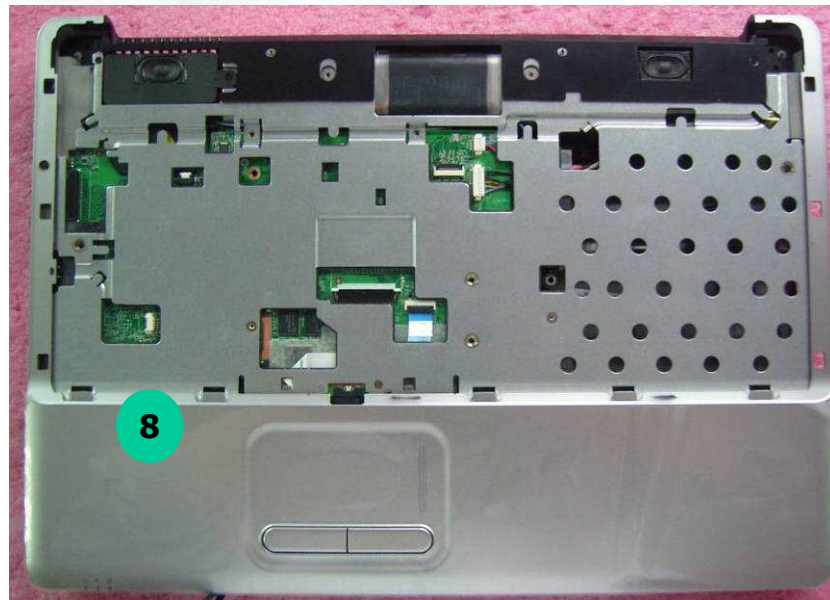


Get Component
5.K/B
6.Middle cover
7.LCD module



Disassemble
Cable
Screw (in the Top side of Base unit)

Disassemble Process-3



Get Component

- 8.U-case module
- 9.Speak module
- 10.USB Board
- 11.Audio BD
- 12.BT
- 13.Main BD
- 14.ODD transfer BD
- 15.L-case module

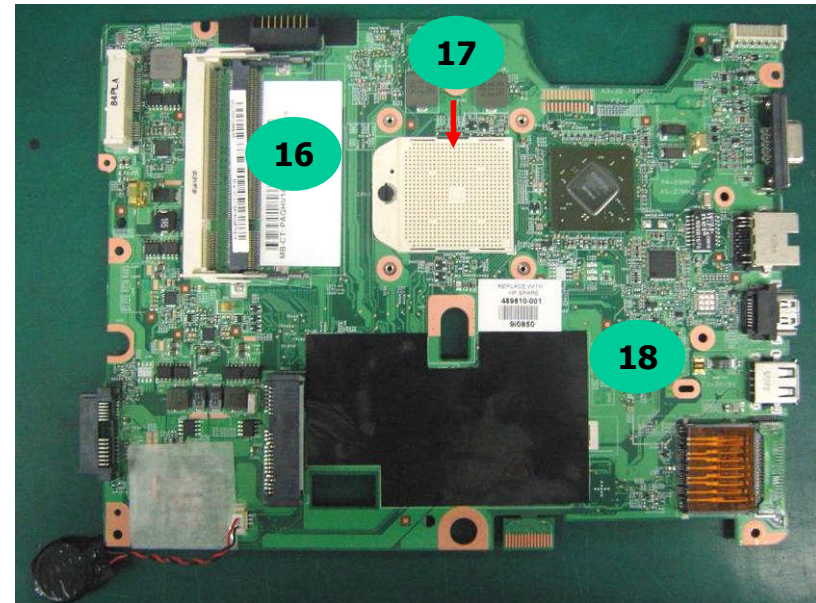
Disassemble item

- Screw (In the top of base units)
- Cable

Disassemble Process-4

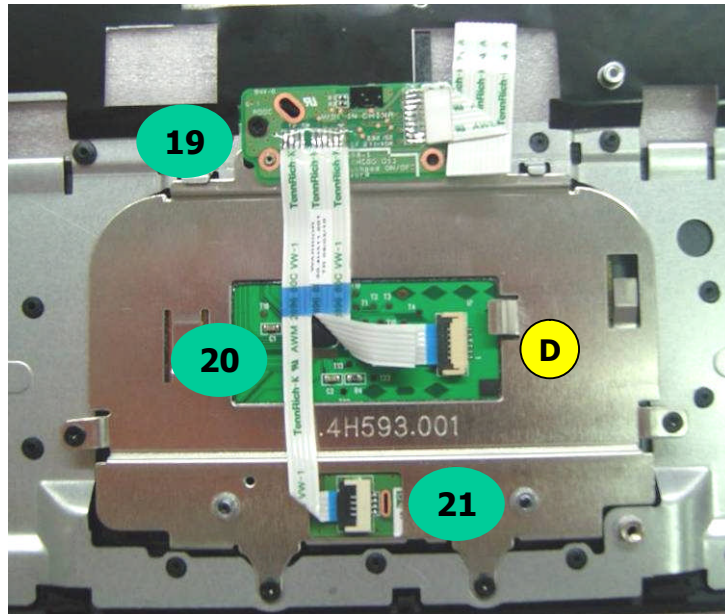


Get Component
16.DIMM
17.CPU
18.MB

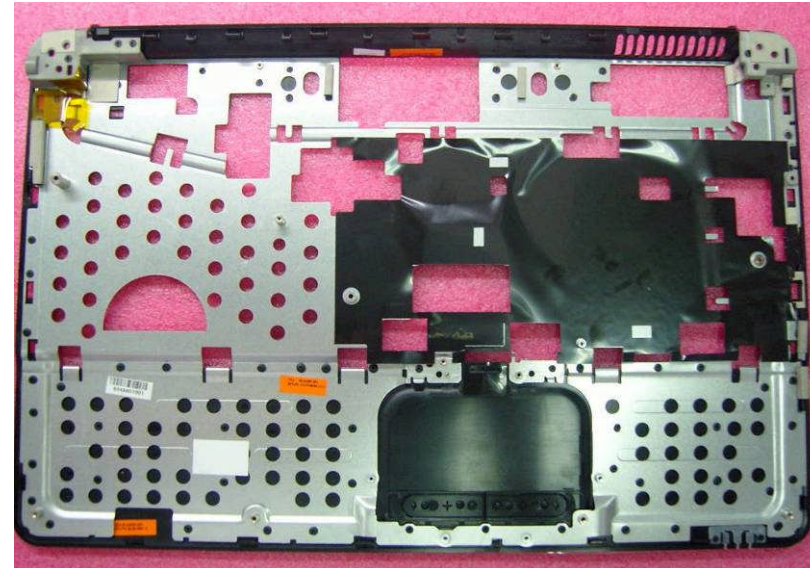


Disassemble item
c. Heat sink

Disassemble Process-5

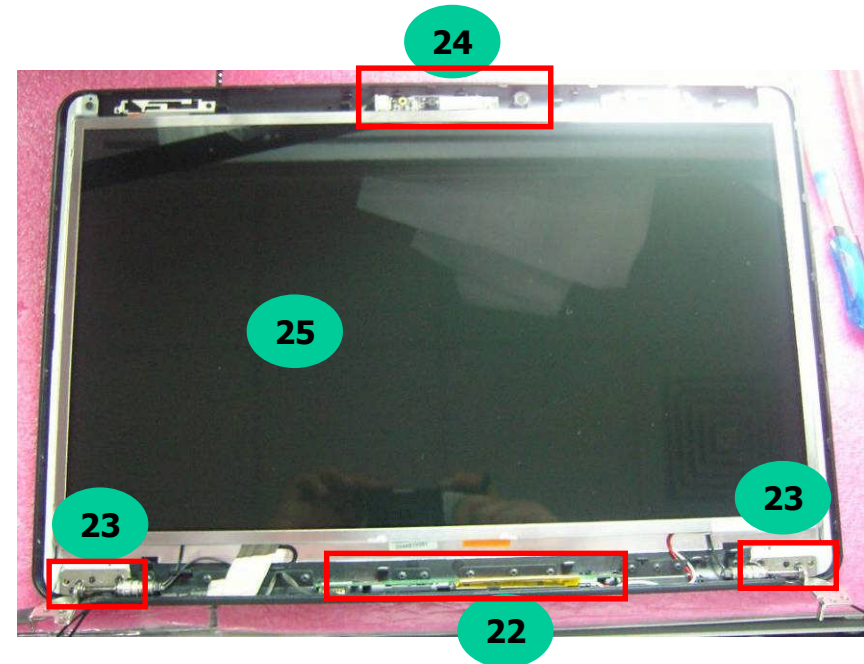


Get Component
19. T/P on-off board
20. T/P board
21. T/P L/R button board



Disassembl item
D.T/P Bracket
screw

Disassemble Process-6



Get Component

- 22.Inveter
- 23.Hinge
- 24.Camare
- 25.LCD

Disassemble item

- E.LCD Bezel
- Screw/Rubber